

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	25	((TATSUO) near2 (KATAOKA)). INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:31
S2	6	((YOSHIKAZU) near2 (AKASHI)). INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:32
S4	38	S1 S2 S3	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/29 15:33
S3	17	((YUTAKA) near2 (IGUCHI)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:33
S5	1	(process or method) board (insulating adj (film or layer)) (conductive near1 layer) (sputtered adj metal adj layer) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:41
S6	2	(process or method) board (insulating adj (film or layer)) (conductive near1 layer) (sputtered adj metal adj layer) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 15:42
S8	7	("6824827" "6613987" "4742009" "5227224" "5130192" "5998739" "5044073").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/29 15:48
S9	0	("2007/0145584").URPN.	USPAT	AND	ON	2008/01/29 15:49
S10	2	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputtered adj metal adj (film or layer)) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/29 16:32
S11	13	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputtered adj metal adj (film or layer)) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 14:44
S12	13	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputtered adj metal adj (film or plane or plate or layer)) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 14:45

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S14	2	S11 S13	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 14:54
S13	132	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 14:54
S15	20	S13 sputtered	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 15:13
S16	13	S12 (sputtered adj metal adj (film or plane or plate or layer))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:06
S17	6	S12 (sputtered adj metal adj (layer))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:09
S20	0	S13 S18	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:26
S18	48	(US-5480730-\$ or US-5364707-\$ or US-6060175-\$ or US-5199163-\$ or US-5326643-\$ or US-4341942-\$ or US-4780957-\$ or US-4830691-\$ or US-4968398-\$ or US-4976808-\$ or US-5200026-\$ or US-5231751-\$ or US-5442145-\$ or US-5569739-\$ or US-5582858-\$ or US-5599582-\$ or US-5621246-\$ or US-5628852-\$ or US-5686702-\$ or US-5736681-\$ or US-5858518-\$ or US-5865934-\$ or US-5889325-\$ or US-6096482-\$ or US-6100582-\$ or US-6124004-\$).did. or (US-6165629-\$ or US-6190493-\$ or US-6214923-\$ or US-6228511-\$ or US-6245432-\$ or US-4347306-\$ or US-4353954-\$ or US-4411982-\$ or US-4592801-\$ or US-4882216-\$ or US-4907039-\$ or US-4982265-\$ or US-5019944-\$ or US-5224265-\$ or US-5232548-\$ or US-5246564-\$ or US-5266446-\$ or US-5359222-\$ or US-5373627-\$ or US-5587341-\$ or US-5589668-\$ or US-5659198-\$).did.	USPAT	AND	ON	2008/01/30 16:26
S21	495	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputter\$3 near2 metal) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:27

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S22	0	S18 S21	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:28
S23	27	(process or method) board (insulating adj film) (conductive adj layer) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:37
S24	0	(process or method) board (insulating adj film) (conductive adj layer) etch\$3 (sputtered adj metal adj layer)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:38
S26	0	S23 S25	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:39
S25	33	board (conductive adj layer) (sputtered adj metal adj layer)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:39
S27	18	(process or method) board (insulating adj film) (conductive adj layer) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome)) sputter\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 16:40
S28	1	(process or method) board (insulating adj (film or layer)) (conductive near1 layer) (sputtered adj metal adj layer) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:34
S31	18	((etch\$3 or dissolv\$3) near2 (nickel and chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:35
S30	1	(process or method) board (insulating adj (film or layer)) ((etch\$3 or dissolv\$3) near2 (nickel and chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:35
S29	1	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel and chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:35
S32	15	(process or method) board ((insulating or polyimide) adj film) (conductive adj layer) etch\$3 (sputtered adj metal adj layer)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/30 17:46

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L1	2	(process or method) board ((liquid or wet) near3 (etch\$3 or dissolv\$3)) ((etch\$3 or dissolv\$3) near3 nickel) ((etch\$3 or dissolv\$3) near3 chrome)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 09:30
L2	5	((liquid or wet) with (etch\$3 or dissolv\$3)) ((etch\$3 or dissolv\$3) near2 nickel) ((etch\$3 or dissolv\$3) near2 chrome)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 09:33
L4	1	3 (remove with (residual with surface))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 09:52
L3	22	(US-20060048963-\$ or US-20070037379-\$ or US-20050258522-\$ or US-20050181542-\$ or US-20020148733-\$ or US-20030142453-\$ or US-20050189136-\$ or US-20010036052-\$ or US-20040099374-\$ or US-20050003673-\$).did. or (US-6824827-\$ or US-5998739-\$ or US-5227224-\$ or US-5130192-\$ or US-5044073-\$ or US-4742009-\$ or US-6613987-\$ or US-6900110-\$ or US-6867073-\$ or US-4921777-\$ or US-6071597-\$ or US-4874483-\$).did.	US-PGPUB; USPAT	AND	ON	2008/01/31 09:52
L5	3	3 (residual with surface)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 09:59
L7	16	(depth near2 (polyimide adj film)) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 11:23
L8	1	(sputtered adj metal adj layer) with ((nickel or Ni) and (chrome or chromium))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 12:16
L9	91	(sputtered near2 layer) with ((nickel or Ni) and (chrome or chromium))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 12:17
L10	62946	(plat\$3 near3 (copper or (copper adj alloy)))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 13:21
L11	19	9 10	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 13:22
L12	2	("2004/0231141").URPN.	USPAT	AND	ON	2008/01/31 14:12

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L14	21	13 (sputter\$3 with copper)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 14:36
L13	42	(US-20060048963-\$ or US-20070037379-\$ or US-20050258522-\$ or US-20050181542-\$ or US-20020148733-\$ or US-20030142453-\$ or US-20050189136-\$ or US-20010036052-\$ or US-20040099374-\$ or US-20050003673-\$ or US-20020009820-\$ or US-20020061424-\$ or US-20030031877-\$ or US-20030132823-\$ or US-20030198828-\$ or US-20030198836-\$ or US-20030222668-\$ or US-20040231141-\$ or US-20050051872-\$ or US-20050098433-\$ or US-20030134273-\$ or US-20030210496-\$).did. or (US-6824827-\$ or US-5998739-\$ or US-5227224-\$ or US-5130192-\$ or US-5044073-\$ or US-4742009-\$ or US-6613987-\$ or US-6900110-\$ or US-6867073-\$ or US-4921777-\$ or US-6071597-\$ or US-4874483-\$ or US-4077854-\$ or US-4582559-\$ or US-4942373-\$ or US-5058250-\$ or US-5099120-\$ or US-5179188-\$ or US-6143427-\$ or US-6689476-\$).did.	US-PGPUB; USPAT	AND	ON	2008/01/31 14:36
L15	7	13 (plating near3 pattern)	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 14:51
L16	1	13 (plating near3 (wiring adj pattern))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 14:52
L17	1	"20050003673".did.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:17
L23	2	("20020148733" "20050258522"). did.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/31 15:22
L22	0	("20020148733" "20050258522"). did.	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:22

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L24	1705	174/254-258.cor. 361/792-795. cor.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/31 15:31
L26	7	24 L25	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:32
L25	132	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) etch\$3 ((etch\$3 or dissolv\$3) near2 (nickel or chrome))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:32
L29	1	24 L28	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:33
L28	13	L27 (sputtered adj metal adj (film or plane or plate or layer))	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:33
L27	13	(process or method) board (insulating adj (film or layer)) (conductive near1 (film or layer)) (sputtered adj metal adj (film or plane or plate or layer)) etch\$3	US-PGPUB; USPAT; USOCR	AND	ON	2008/01/31 15:33